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*Furukawa, Y.; Kokubo, T.; Struyf, H.; Maenhoudt, M.; Vanhaelemeersch, S.; Gravesteijn, D.*

Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International , 2002  
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[\[Abstract\]](#) [\[PDF Full-Text \(381 KB\)\]](#) **CNF**

2 **A novel CMP application on the fabrication of dual-damascene struc**  
**advanced copper/low-k interconnections**

*Shao-Chung Hu; Hsueh-Chung Chen; Liang-Yuan Fang; Chien-Mei Wang; Ch Hung; Wen-Yi Hsieh; Po-Wen Yen*  
Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International , 2002  
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[\[Abstract\]](#) [\[PDF Full-Text \(352 KB\)\]](#) **CNF**

3 **Stopper-less hybrid low-k/Cu DD structure fabrication combined w**  
**CMP**

*Usami, T.; Nanbu, H.; Sugai, K.; Tagami, M.; Miyamoto, H.*  
Interconnect Technology Conference, 2002. Proceedings of the IEEE 2002 International , 2002  
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-	1147	( (trench via hole contact open\$3 groov\$ reces\$4 plug) and (hard same mask\$3) and (resist photoresist) ) and ((trench via hole contact open\$3 groov\$ reces\$4 plug) same (hard adj2 mask\$3))	USPAT	2002/10/21 13:36
-	105	( (trench via hole contact open\$3 groov\$ reces\$4 plug) same (hard same mask\$3) and (resist photoresist) ) and (second same (hard same mask\$3))	EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:50
-	90	( (trench via hole contact open\$3 groov\$ reces\$4 plug) same (hard same mask\$3) and (resist photoresist) ) and (second same (hard adj2 mask\$3))	EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:50
-	10	(( (trench via hole contact open\$3 groov\$ reces\$4 plug) same (hard same mask\$3) and (resist photoresist) ) and (second same (hard adj2 mask\$3))) and (second adj2 (hard adj2 mask\$3))	EPO; JPO; DERWENT; IBM_TDB	2002/10/21 13:52
-	24	( (trench via hole contact open\$3 groov\$ reces\$4 plug) and ((hard same mask\$3) same (tungsten titanium tantalum)) and (resist photoresist) ) and (second adj2 (hard adj2 mask\$3))	USPAT	2002/10/21 13:53
-	1731	(etch\$3 same (hard adj2 mask\$3)) and (trench via hole open\$3)	USPAT	2002/11/07 17:15
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-	135	(( (tch\$3 sam (hard adj2 mask\$3)) and (trench via hole pen\$3)) and (second sam hard)) and partial\$9) and (partial\$9 sam hard)	USPAT	2002/11/07 17:19
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-	641	438/942,639,717.ccls.	USPAT	2002/12/09 16:38
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